



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CJCv Series Board Mound Telephone Jack	SPEC.NO.: SPCJ070B
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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA-364	Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CJCv88HE1AB

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings

REVIEWED : Eisley APPROVED : Sun VERIFIED : Jessie .

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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.5A DC 125V AC (r.m.s.)
7.2	Contact resistance	Subject mated contacts assembled housing to 20 mV max. 100 mA .Measured from plug side to PCB side. EIA-364-23C	Less than 20 mΩ (Initial) Less than 50 mΩ (Final) see notes (a)
7.3	Dielectric strength	Mated connectors apply 1500±5% V AC 2250 V DC for 6 Sec.1 mA between adjacent terminal or ground. EIA-364-20C	No breakdown
7.4	Insulation resistance	Mated connector with 500±10% V DC between adjacent contacts or ground. EIA-364-21C	More than 500 MΩ (Initial / Final)
7.5	LED Functional Test	Activate LEDs at application current (20 mA DC) and voltage (20 Volts DC).	When LEDs are present, all LED colors illuminate and meet visual requirements.

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Durability	Mate and unmated for 750 cycles Operation Speed : 10~20 cycles per minute EIA-364-09C	Appearance: No damage Contact resistance Less than 50 mΩ
8.2	Mating / Un-mating force	Measure force to mate samples at speed 25±3mm per minute with plug latch depressed EIA-364-13D	2.34 Kgf (23 N) Max.
8.3	Normal Force	Mating connectors and measure the force of the contact area, using an FCC compliant modular plug. EIA-364-04	100 gram force minimum (The pressed height is 1/2 of the terminal bouncing height.)

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9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature Life	Mated connectors and expose to $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for 500 hours, Upon completion of the exposure period the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed. EIA-364-17B Method A, Test Condition 3, Test Time Condition C.	Appearance: No damage Contact resistance: To pass para 7-2
9.2	Humidity	At a temperature of $40 \pm 2^{\circ}\text{C}$ and relative humidity of 90-95% for 96 hours. Then, be left alone for 1 to 2 hours in a room ambient and test in the time. EIA-364-31B	Appearance: No damage Contact resistance: To pass para 7-2 Dielectric strength: To pass para 7-3
9.3	Salt spray	Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage Contact resistance: Less than twice of initial

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	ITEM	TEST CONDITION	REQUIREMENT
9.4	Solder ability	Soldering time: 3 ± 0.5 second Soldering pot: $245 \pm 5^{\circ}\text{C}$ EIA-364-52	Minimum: 95% of immersed area
9.5	Resistance to soldering heat	Soldering time: 5 second max. Soldering pot: $260 \pm 5^{\circ}\text{C}$ Recommend Wave Soldering Profile (11.) EIA-364-56D	No damage

Notes:

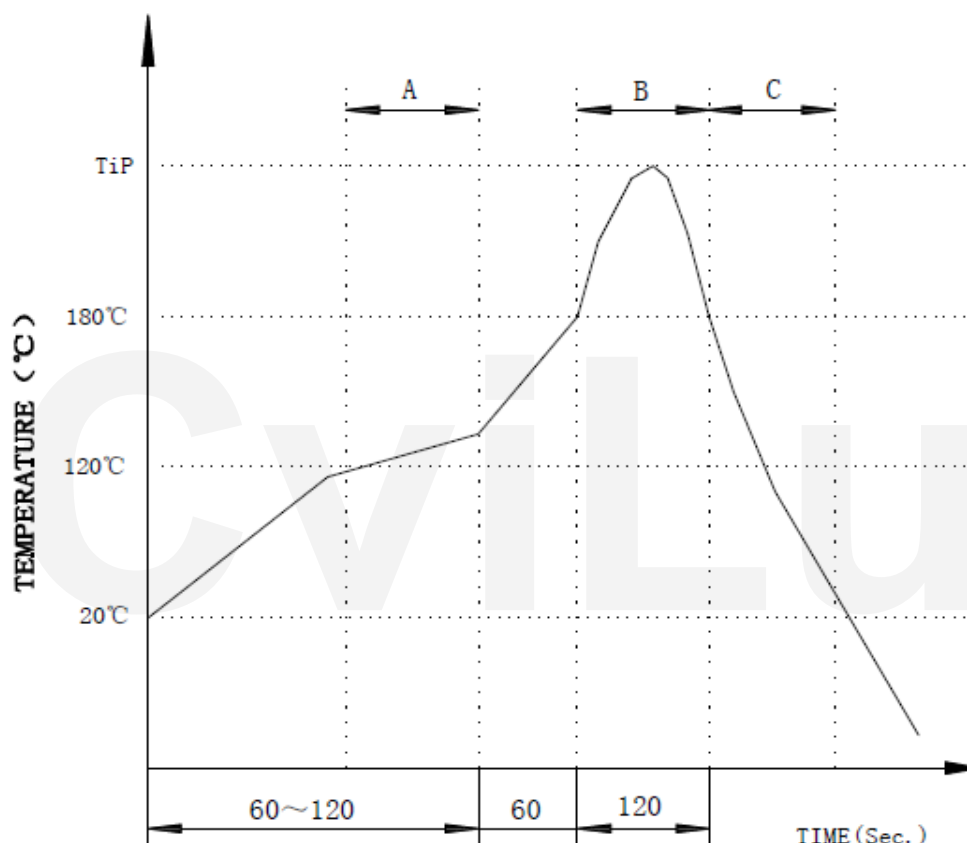
- (a) : The test result does not include the resistance of cable and internal resistance of contact wire.
(b) : Do not perform “IR reflow soldering test” for wave soldering product.

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10. OPERATING TEMPERATURE RANGE: -40 to + 85 °C
STORAGE TEMPERATURE RANGE: -40 to + 85 °C

11. Recommend Wave Solder Profile



A. Preheating B. Soldering C. Gradual Cooling

Tip temperature: 260±5 °C.

Tip temperature time: 5 Sec Max.

Tip melting point of Sn 96.5 / Ag3 / Cu 0.5: 217 °C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function